



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC014N04LS		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA004974748						
<b>Package</b>		PG-TDSON-8-26		<b>Weight*</b>		114.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.009	0.88	0.88	8800	8800
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.05		452	
	non noble metal	copper	7440-50-8	51.740	45.11	45.17	451103	451690
	noble metal	gold	7440-57-5	0.045	0.04	0.04	391	391
wire	organic material	carbon black	1333-86-4	0.082	0.07		715	
encapsulation	plastics	epoxy resin	-	6.479	5.65		56491	
	inorganic material	silicondioxide	60676-86-0	34.448	30.03	35.75	300333	357539
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12132	12132
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1690	1690
solder	non noble metal	tin	7440-31-5	0.029	0.03		253	
	noble metal	silver	7440-22-4	0.036	0.03		317	
	non noble metal	lead	7439-92-1	1.387	1.21	1.27	12092	12662
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
heat sink clip	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.635	0.55		5540	
	non noble metal	copper	7440-50-8	17.131	14.94	15.51	149361	155096
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com